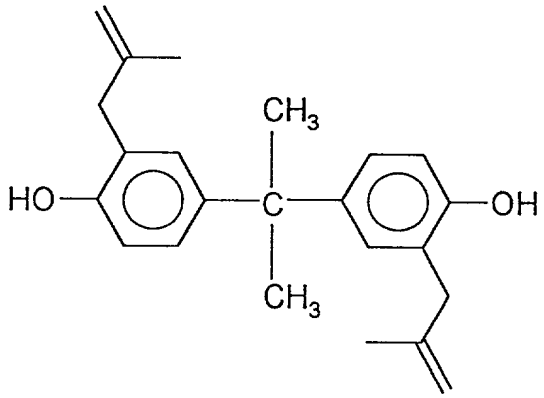
WHAT IS CLAIMED IS:

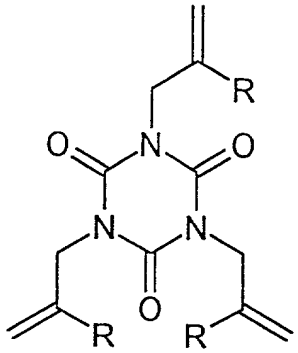
1. A laminated board comprising a prepreg sheet or prepreg sheets prepared by impregnating a reinforcing fiber material with the thermosetting low-dielectric resin composition comprising a component (a): siloxane-modified polyimide, component (b): a compound containing 2 methylallyl groups and having the following formula (1) or a compound containing 3 allyl groups or 3 methylallyl groups and having the following formula (1A), and component (c): a compound containing at least 2 maleimide groups.

Formula (1):



(1)

Formula (1A):



(1A)

wherein R is a hydrogen atom or methyl group.

2. The laminated board according to claim 1, wherein the laminated board is a metal-clad laminate formed of the laminated

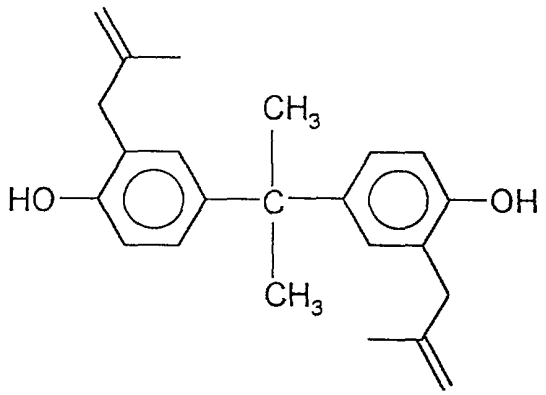
board and a metal foil or foils which is or are stacked on and integrated with one surface or both surfaces of the laminated board.

3. The laminated board according to claim 2, wherein the metal-clad laminate is formed of a sheet or sheets of a prepreg impregnated with the thermosetting low-dielectric resin composition in a semi-cured state or a cured state and a metal foil or metal foils is/are laminated on and integrated with the prepreg.

4. The laminated board according to claim 1, wherein the reinforcing fiber material is a fabric or a non-woven fabric formed of at least one member selected from the group consisting of an aramid fiber, an aromatic polyester fiber and a tetrafluorocarbon fiber.

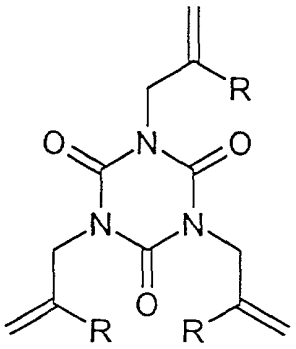
5. The laminated board according to claim 1, wherein the metal foil is a metal foil formed of at least one member selected from the group consisting of copper, cupronickel, silver, iron, 42 alloy and stainless steel.

6. A circuit laminate material comprising either a peeling-off layer or a metal foil and the thermosetting low-dielectric resin composition comprising a component (a): siloxane-modified polyimide, component (b): a compound containing 2 methylallyl groups and having the following formula (1) or a compound containing 3 allyl groups or 3 methylallyl groups and having the following formula (1A), and component (c): a compound containing at least 2 maleimide groups.
Formula (1):



(1)

Formula (1A):

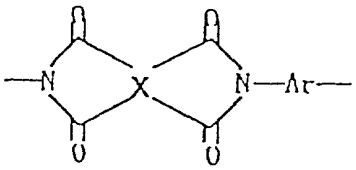


(1A)

wherein R is a hydrogen atom or methyl group, which thermosetting low-dielectric resin composition is an adhesive layer laminated on one surface of the peeling-off layer or the metal foil.

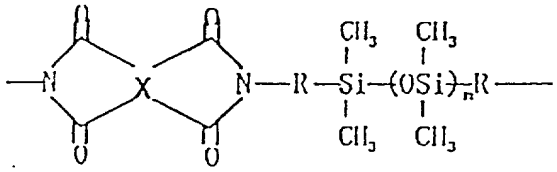
7. The circuit laminate material according to claim 6, wherein the siloxane-modified polyimide as a component (a) contains 90 to 40 mol% of at least one of structural units of the following formula (2a) and 10 to 60 mol% of at least one of structural units of the following formula (2b) when the component (b) is the compound of the formula (1).

Formula (2a):



(2a)

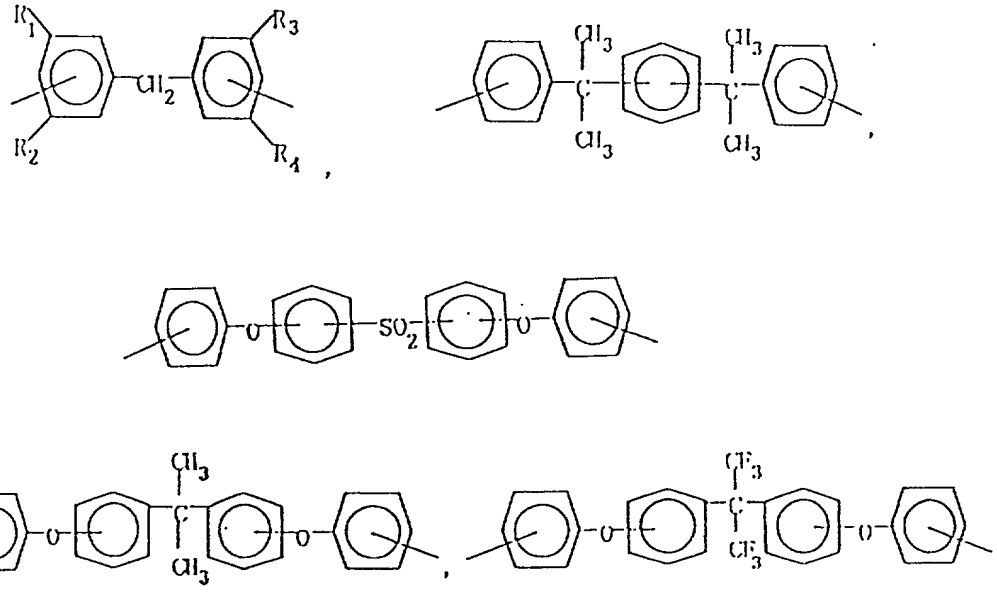
Formula (2b):



(2b)

wherein X is a tetravalent aromatic group and is any one of a 3,3',4,4'-diphenylsulfone structure, a 3,3',4,4'-biphenyl structure and 2,3',3,4'-biphenyl structure, Ar is a divalent group selected from aromatic-ring-possessing groups of the following formula (3), R is $-CH_2OC_6H_4-$ whose methylen group is bonded to Si or an alkylene group having 1 to 10 carbon atoms, and n is an integer of 1 to 20,

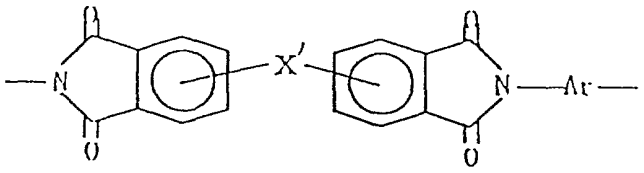
Formula (3):



wherein each of R_1, R_2, R_3 and R_4 is independently a hydrogen atom, or an alkyl or alkoxy group having 1 to 4 carbon atoms provided that all of these are hydrogen atoms in no case.

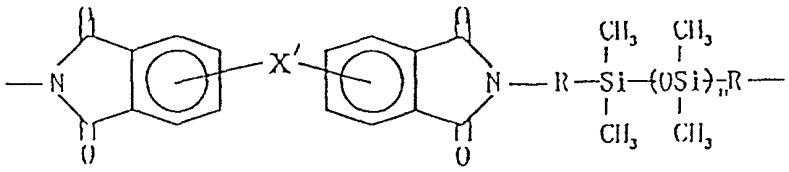
8. The circuit laminate material according to claim 6, wherein the siloxane-modified polyimide as a component (a) contains 90 to 40 mol% of at least one of structural units of the following formula (2a') and 10 to 60 mol% of structural units of the following formula (2b') when the component (b) has the formula (1A).

Formula (2a'):



(2a')

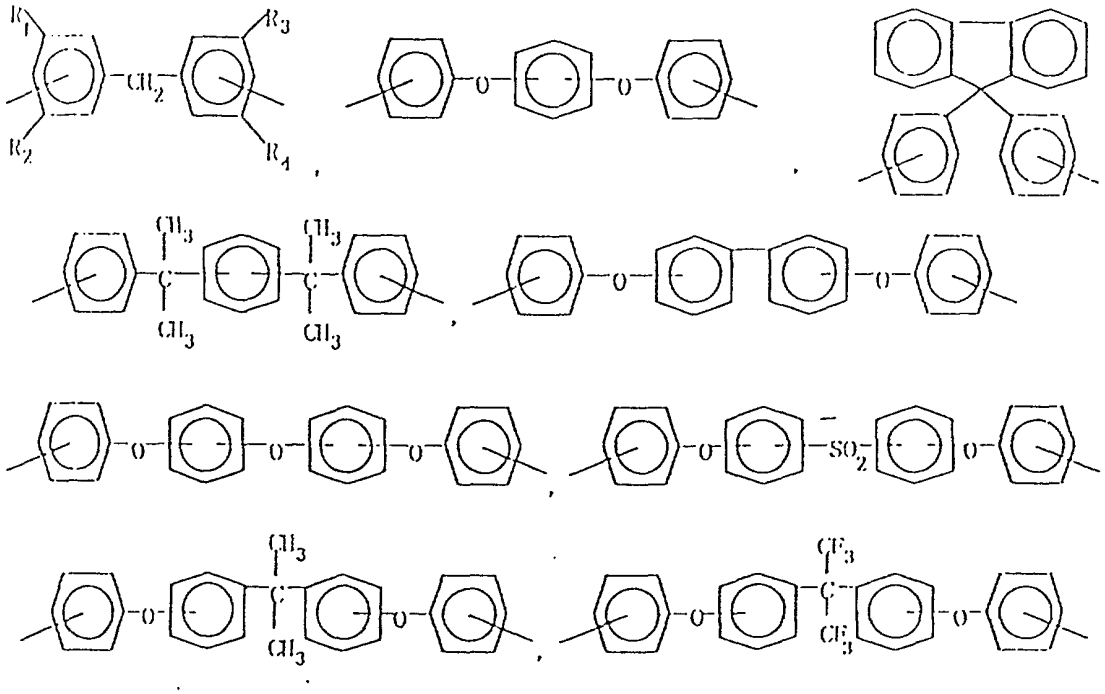
Formula (2b'):



(2b')

wherein X is a direct bond or any one of binding groups of $-O-$, $-SO_2-$, $-CO-$, $-C(CH_3)_2-$, $-C(CF_3)_2-$ and $-COOCH_2CH_2OCO-$, Ar is a divalent group selected from aromatic-ring-possessing groups of the following formula (3A), R is $-CH_2OC_3H_4-$ whose methylen group is bonded to Si or an alkylene group having 1 to 10 carbon atoms, and n is an integer of 1 to 20,

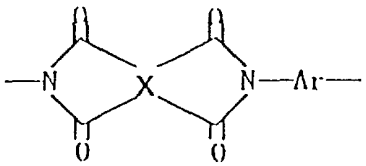
Formula (3A):



wherein each of R_1, R_2, R_3 and R_4 is independently a hydrogen atom or an alkyl or alkoxy group having 1 to 4 carbon atoms provided that all of these are hydrogen atoms in no case.

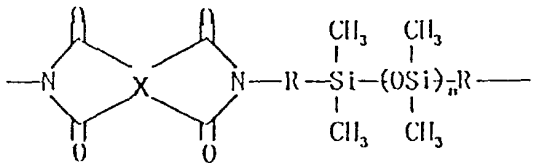
9. The circuit laminate material according to claim 6, wherein the siloxane-modified polyimide as a component (a) contains 90 to 40 mol% of at least one of structural units of the following formula (2a) and 10 to 60 mol% of structural units of the following formula (2b) when the component (b) has the formula (1A).

Formula (2a):



(2a)

Formula (2b):



(2b)

wherein X is a tetravalent aromatic group and is any one of a 3,3',4,4'-diphenylsulfone structure, a 3,3',4,4'-biphenyl structure and 2,3',3,4'-biphenyl structure, Ar is a divalent group selected from aromatic-ring-possessing groups of the following formula (3A) recited claim 4, R is $-CH_2OC_6H_4-$ whose methylen group is bonded to Si or an alkylene group having 1 to 10 carbon atoms, and n is an integer of 1 to 20.

10. The circuit laminate material according to claim 6, wherein the metal foil has a thickness of 10 to 300 μm.

11. The circuit laminate material according to claim 6, wherein the adhesive layer has a peeling-off layer formed on one surface opposite to the metal foil or the film.